

PFM-540I

AMD Geode LX800 AMD LX +CS5536 PC/104 Board

Thermal Image Analysis Report

Report NO: 06E080042

Release Date: Dec 01, 2006

2006/12/01

Issue Stamp

Wenyuan Yang

Manager

Eva Yeh

Test Engineer

Thermal Image Analysis

I . Model Name: PFM-540I A1.0

II . Description: AMD Geode LX800 AMD LX + CS5536 PC/104 Board

III . Date: Dec 01, 2006

IV. Measure Site: AAEON QE Dept.

V. Issued by : Eva Yeh

VI. Equipment:

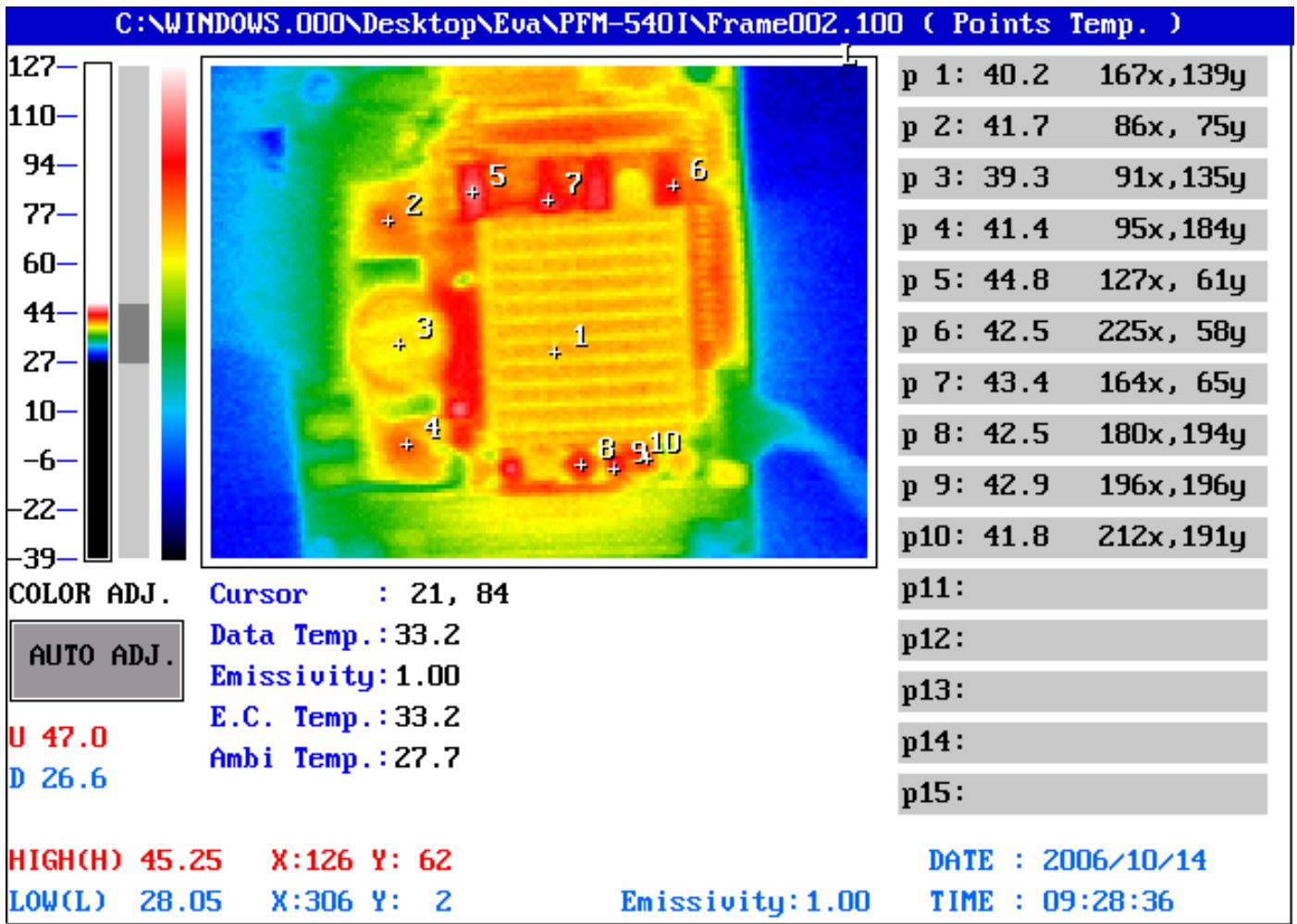
TVS-100 series by NIPPON AVIONICS CO., LTD.

VII. Simulation Environment:

- **Temperature: Component Side-1 : 27.7°C , Component Side-1 : 28.1°C**
- **CPU : AMD Geode-GX-MMX 500MHz CPU**
- **RAM : Kingston KVR333X64SC25 NANYA HY5DU121622CTP-D43 512MB**
- **BIOS : PFM-540I BIOS Rev:1.0 (10/11/2006)**
- **CF Card : N/A**
- **HDD1: Seagate ST3120026AS/P 120GB ATA-100**
- **Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 2**
- **Take Picture Time: After Power on 2 hours.**

Temperature Profile Test:

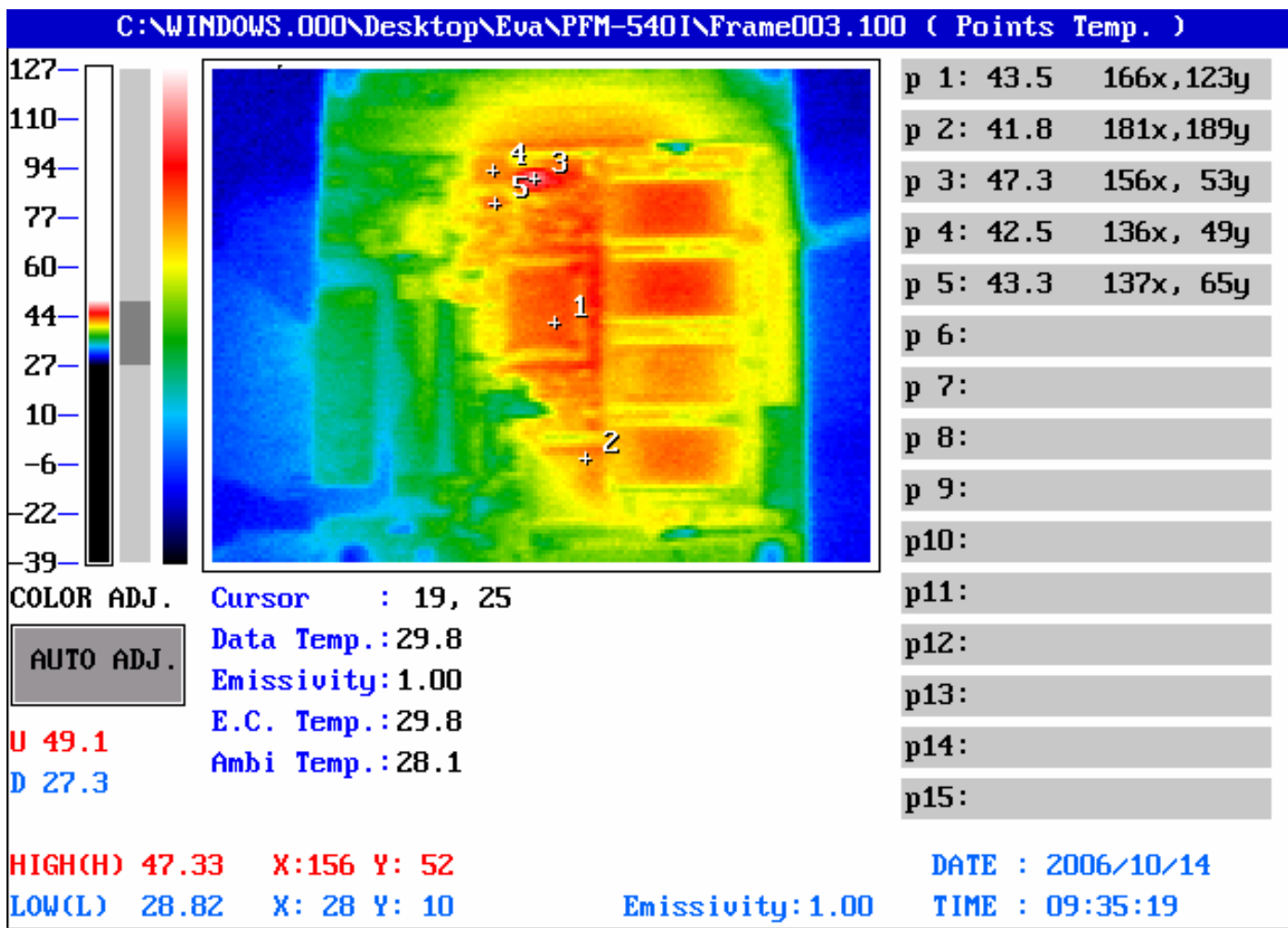
Component Side-1:



Point	Position	Describe	Tc (°C)	Tm (27.7 °C)	Tm (60°C)	Note
1	U5	(TF)AMD CPU.BGU481.LX-800.500MHz.1.25V.AMD.ALXD800EEXJ2VD	85	40.2	72.5	
2	U7	(TF)IC.SMD.LQFP 100P PCI Ethernet Chip.RELTEK.RTL8139DL	100	41.7	74	
3	U6	(TF)IC.SMD 208PBGA.I/O Companion.Multi-Function South Bridge .AMD.CS5536AD	110	39.3	71.6	
4	U3	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L	100	41.4	73.7	
5	U10	(TF)IC.SMD.SSOP28.Clock Generator.ICS.MK1491-09FLN	100	44.8	77.1	
6	U9	(TF)IC.SMD.SSOP RS232 Driver ESD 15KV.AD.ADM213EARSZ	115	42.5	74.8	
7	U8	(TF)IC.SMD.SO8.RS-485 Transceiver.Analog.ADM485JRZ	115	43.4	75.7	
8	L3	(TF)COIL.3.3uH.+/-20%.DCR=0.034Ohm.Idc=3A.SMD.5.8*5.2*4.5mm.GO TREND.GSDR54P-3R3M	115	42.5	74.8	
9	U1	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER.IR.IR3624MTRPBF	100	42.9	75.2	
10	Q1	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A. Rds=21/27mohm.Vgs=10/4.5V.ANPEC.APM7313KC-TRL	125	41.8	74.1	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
 2. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification

Component Side-2:



Point	Position	Describe	Tc (°C)	Tm (28.1 °C)	Tm (60°C)	Note
1	SKT1	(TF)IC.SMD.4M bit Flash Memory for intel (Firmware Hub). SST49LF004B-33-4C-NHE.(Rev.CA)	85	43.5	75.4	
2	U28	(TF)IC.SMD.QFP128P Super I/O.ITE.IT8712F-A/IX-L	100	41.8	73.7	
3	Q7	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A. Rds=21/27mohm.Vgs=10/4.5V.ANPEC.APM7313KC-TRL	125	47.3	79.2	
4	TC3	(TF)SP CAP.150uF.6.3V.20%.D(7.3*4.3*2.8mm).18mOhm SMD. Panasonic.ECGUD0J151ER	105	42.5	74.4	
5	D7	(TF)D Schottky.SMD.SOT-23.PHILIPS.BAT54S	100	43.3	75.2	

3. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
 4. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification